

IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

Applicant: **Chae, et al.**

Case: **APPM/8501/ETCH/DRIE**

Serial No.: **10/706,902**

Filed: **November 11, 2003**

Examiner: **Tran, Binh X.**

Group Art Unit: **1765**

Conf. No.: **7748**

Title: **SELECTIVE ETCH PROCESS OF A SACRIFICIAL LIGHT ABSORBING
MATERIAL (SLAM) OVER A DIELECTRIC MATERIAL**

Mail Stop: AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL RESPONSE TO OFFICE ACTION DATED JULY 18, 2006

S I R:

In response to the Office Action dated July 18, 2006, having a shortened statutory period for response expired on October 18, 2006, please enter this Supplemental Response and reconsider the pending application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 50-3562, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.